

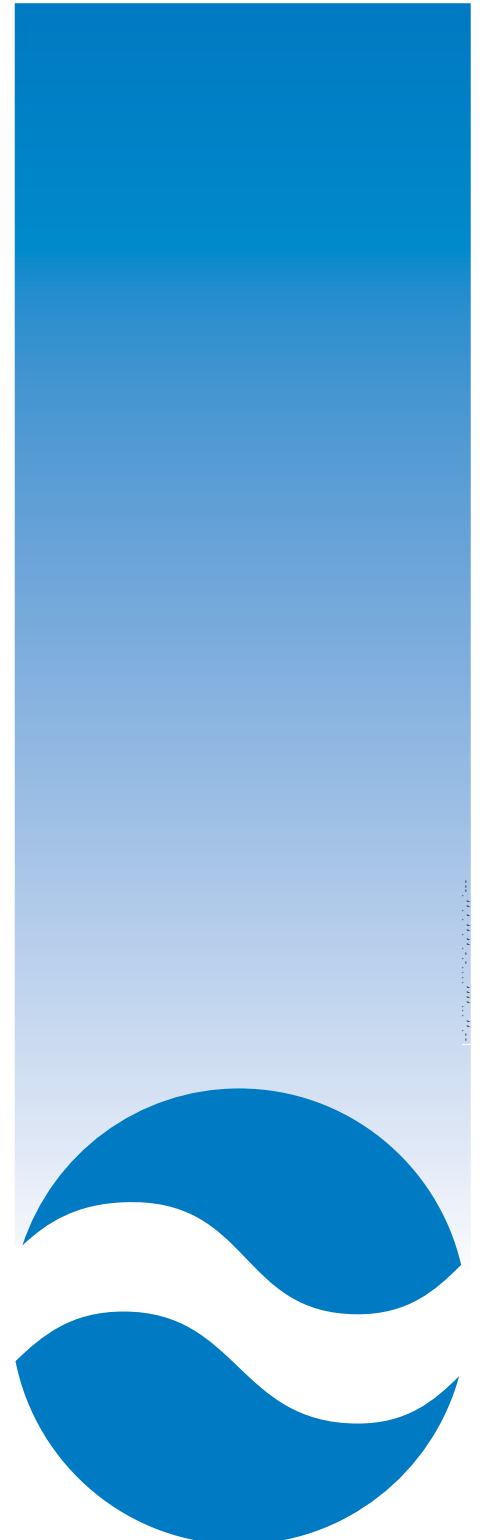
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Space and Military
Applications Electronic
Hardware Addendum to
IPC J-STD-001G
Requirements for
Soldered Electrical
and Electronic
Assemblies



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IPC J-STD-001GS

Space and Military Applications Electronic Hardware Addendum to IPC J-STD-001G Requirements for Soldered Electrical and Electronic Assemblies

Developed by the Space Electronic Assemblies J-STD-001 Addendum Task Group (5-22as) of the Assembly & Joining Processes Committee (5-20) of IPC

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Space and Military Applications Electronic Hardware Addendum to IPC J-STD-001G Requirements for Soldered Electrical and Electronic Assemblies

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